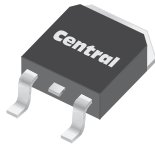


Material Composition Specification

DPAK Case



Device average mass 297 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.75%	2.23	Si	7440-21-3	0.75%	2.23	7,508
leadframe	Cu alloy	52.54%	156	Cu	7440-50-8	52.46%	155.8	524,570
				Fe	7439-89-6	0.08%	0.24	808
die attach	high temperature solder paste	5.12%	15.2	Pb	7439-92-1	4.73%	14.06	47,339
				Sn	7440-31-5	0.26%	0.76	2,559
				Ag	7440-22-4	0.13%	0.38	1,279
encapsulation*	EMC	38.7%	115	silica	7631-86-9	26.33%	78.2	263,255
				epoxy resin	29690-82-2	7.74%	23.0	77,428
				phenol resin	9003-35-4	3.87%	11.5	38,690
				Sb ₂ O ₃	1309-64-4	0.38%	1.14	3,838
				Br	7726-95-6	0.38%	1.14	3,838
	EMC GREEN	38.7%	115	silica (fused)	60676-86-0	29.8%	88.5	297,975
				epoxy resin	29690-82-2	3.87%	11.5	38,720
				phenol resin	9003-35-4	3.76%	11.16	37,575
				carbon black	1333-86-4	0.12%	0.345	1,162
				metal hydroxide	1309-42-8	1.16%	3.45	11,616
plating**	tin/lead process	2.89%	8.58	Sn	7440-31-5	2.6%	7.72	25,993
				Pb	7439-92-1	0.29%	0.86	2,896
	matte tin	2.89%	8.58	Sn	7440-31-5	2.89%	8.58	28,888

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)